

ABSTRACT OF THE DISCLOSURE

EPOXY RESIN MOLDING MATERIAL FOR SEALING ELECTRONIC PARTS AND SEALED SEMICONDUCTOR DEVICE USING THE SAME

An epoxy resin molding material comprising an epoxy resin, a phenolic resin and a powder flexibilizer which has a core-shell structure composed of a solid silicone core and an organic polymer shell is a reliable epoxy resin molding material for sealing electronic parts which is excellent in, for example, thermal shock resistance and reflow soldering resistance, and is free from the troublesome deterioration in, for example, the appearance and marking properties of molded products, and to provide a semiconductor sealed by the molding material.